



SMD Comm X8G HT150C, Ceramic, 1,100 pF, 5%, 200 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1812, 2.3 mm



General Information		
Series	SMD Comm X8G HT150C	
Style	SMD Chip	
Description	SMD, MLCC, High Temperature, Ultra-Stable	
Features	High Temperature, Ultra-Stable	
RoHS	Yes	
Termination	Tin	
Marking	No	
AEC-Q200	No	
Typical Component Weight	67 mg	
Shelf Life	78 Weeks	
MSL	1	

Dimensions		
Chip Size	1812	
L	4.5mm +/-0.3mm	
W	3.2mm +/-0.3mm	
Т	1mm +/-0.10mm	
S	2.3mm MIN	
В	0.6mm +/-0.35mm	

Т	1mm +/-0.10mm
S	2.3mm MIN
В	0.6mm +/-0.35mm
Packaging Specifications	

4000

Packaging

Packaging Quantity

Specifications		
Capacitance	1,100 pF	
Measurement Condition	1 kHz 1.0Vrms	
Tolerance	5%	
Voltage DC	200 VDC	
Dielectric Withstanding Voltage	500 VDC	
Temperature Range	-55/+150°C	
Temp. Coefficient	X8G	
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms	
Dissipation Factor	0.1% 1 kHz 1.0Vrms	
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours	
Insulation Resistance	100 GOhms	

Aging Rate	0% Loss/Decade Time is 1000 Hou
Insulation Resistance	100 GOhms

T&R, 330mm, Plastic Tape

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

Generated 05/04/2025 © 2006 - 2025 YAGEO